

Funding Opportunity – Commercial Fabrication Facilities GUIDE: Pre-Application and Application Document Checklists

Overview

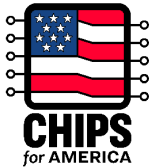
The tables below are summaries of the material and information potential applicants will be asked to submit as part of a pre-application and full application. Further detail can be found in Section IV.H. of the CHIPS Incentives Program – Commercial Fabrication Facilities Notice of Funding Opportunity (NOFO), “Content and Form of Pre-Application,” and Section IV.I. of the NOFO, “Content and Form of Full Application Submission.”

Applications can include more than one project.¹ For those applications with multiple projects, some questions may require one upload for each project (and in some cases, an overarching description of all projects). Some questions may require completion via a web form. Potential applicants will have the opportunity to upload optional supporting documents for required items throughout the application.

Disclosure:

The tables below are not intended to be inclusive of all pre-application and full application requirements and potential applicants should not rely on the tables in place of Sections IV.H and IV.I the NOFO. Any conflicts between information in this document and the NOFO must be resolved in favor of the NOFO, which is the official program document.

¹ “Project” refers to a set of capital expenditures for the construction, expansion, or modernization of a single facility, as well as related workforce development or operating costs proposed to be covered with CHIPS Incentive funds.



Pre-Application Checklist

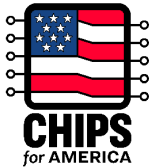
Applicants for leading-edge facilities will be able to submit their pre-application in the [CHIPS Incentives Program application portal](#) on or after March 31, 2023. Applicants for current-generation, mature-node facilities, and back-end production facilities will be able to submit their pre-applications on or after May 1, 2023. Pre-applications can be submitted a minimum of 21 days after statement of interest submission, provided the pre-application is open for the relevant type of facility.

Information in blue will become available to potential applicants on the day the pre-application becomes available in the application portal.

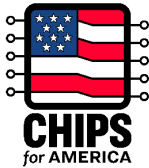
The complete set of requirements for submitting the pre-application are located in the NOFO at Section IV.H.

Template / web form available when application portal goes live

Section	Requested submission	Format	Summary of Contents
Cover Page	1. Pre-Application Cover Page	Web form	Application title, applicant organization information, applicant point of contact, partnership information
Project Plan	2. Project Plan Narrative	PDF and web form	Description of project(s), consortium description (if applicable), cluster profile, estimated project timeline, summary narrative addressing evaluation criteria, CHIPS Incentives justification, and applicant profile
Financial Information	3. Financial Information Narrative	PDF	Financial information narrative including detail on facility ownership structure, project sources and uses of funds, company financials, and summary financials for the project
	4. Facility Ownership Structure	PDF	Formal legal entity and organizational structure for the proposed project(s), including relationship with ultimate corporate parent, if applicable
	5. Project Sources and Uses of funds	Excel template and web form	Details on applicant’s proposal for sources and uses of funds. Complete for each project individually and one that is cumulative for the entire set of proposed projects, if applicable
	6. Company Financials	PDF or Excel	Financial statements, key performance metrics, details on leverage and related debt coverage metrics and ratings
	7. Summary Financials for the Project	Excel and PDF	Project(s) cash flow, income statement, and balance sheet projections through the end of the facility’s useful life, and relevant metrics, in Microsoft Excel; also, a summary narrative and supporting evidence for key assumptions in models.
	8. CHIPS Incentives Request	Web form	Summary of requested dollar amounts for CHIPS Direct Funding and Loan and/or Loan Guarantees



Section	Requested submission	Format	Summary of Contents
	9. CHIPS Incentives Request narrative	PDF	Description for how financial information submitted supports a conclusion that the CHIPS Incentives requested will incentivize the potential applicant to make investments that would not occur in absence of the incentives; also, explanation of how CHIPS incentives requested were sized, and justifications for size and appropriateness of request, and the resulting project IRR.
Environmental Questionnaire	10. Environmental Questionnaire	PDF template	Questionnaire regarding relevant environmental considerations
Workforce Development Information	11. Workforce Development Narrative	PDF and web form	Approach to recruiting, training, and retaining a diverse and skilled set of facility workers



Full Application Checklist

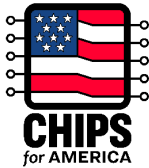
Applicants for leading-edge facilities will be able to submit their full application in the CHIPS Incentives Program application portal on or after March 31, 2023. Applicants for Current-Generation, Mature-Node facilities, and Back-end Production facilities will be able to submit their full applications on or after June 26, 2023. Full applications may be submitted 21 days after statement of interest submission, provided applications are open for the relevant type of facility.

Note that the same information will be asked of all applicants with differences only in the structure of the request (i.e., while the chart below references PDFs, Current and Mature-Generation applicants may be asked to input information directly into the application portal as the application portal goes through ongoing enhancements).

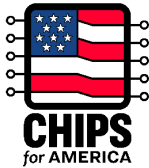
The complete set of requirements for submitting the full application are located in the NOFO at Section IV.I.

Available when full application portal goes live for leading-edge facilities

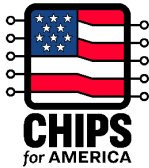
Section	Requested submission	Format	Max pages (Excluding supporting attachments)	Summary of Contents
Cover Page	1. Full application cover page	Web form	N/A	Title of application, applicant organization information, applicant point of contact, partnership information
Covered Incentive	2. Letter(s) from State/Local entity	PDF	N/A	Letter(s) from state or local government entity demonstrating that the applicant has been offered a qualifying covered incentive
Description of Project(s)	3. Description of Project(s)	PDF (and web form, if available)	15 for overarching description + 15 per project	Summary of project(s), consortium description (if applicable), cluster profile, timeline for project(s), summary narrative addressing evaluation criteria, and CHIPS incentives justification
Applicant Profile	4. Descriptive Information about the Applicant	PDF (and web form, if available)	N/A	Information related to the applicant’s businesses, applicant company’s business profile, key products manufactured, end markets, and competitors, and any existing or planned operations in foreign countries of concern.
	5. Company Financials	PDF or Excel	N/A	Financial statements, key financial metrics, statistical ratings organizations reports/ratings.
	6. Equity capital structure	PDF or Excel (and web form, if available)	N/A	If applicable, detailed information on shareholders, shares, and market valuation; information regarding planned equity issuances
	7. Outstanding Debt	PDF or Excel	N/A	Detailed debt schedule, description of planned debt issuances



Section	Requested submission	Format	Max pages (Excluding supporting attachments)	Summary of Contents
Alignment with Economic Resilience and National Security Objectives	8. Description of alignment with CHIPS Program goals	PDF (and web form, if available)	30	How the project(s) meets economic and national security objectives, including cybersecurity practices, supply chain resilience and risk management, and foreign control disclosures
Commercial Strategy	9. Description of Commercial Strategy	PDF (and web form, if available)	15 per project	Commercial strategy, including end-market demand, market position and competitor landscape, stability of supplies and materials, and improvement plans
Financial Information	10. Financial Information Narrative	PDF	20	Detailed description of project financial plan, including sources and uses of funds, cash flow projections, key equity return and debt service metrics, CHIPS incentives request, sensitivity analyses, and supporting evidence for key assumptions
	11. Project Sources and Uses of funds	Excel template (and web form, if available)	N/A	Details on applicant’s proposal for sources and uses of funds, for each project individually as well as cumulatively for the entire set of proposed projects
	12. Project Cash Flow, Balance Sheet, and Income Statement Projections (one per project)	Excel	N/A	Project(s) cash flow, income statement, and balance sheet projections through the end of the facility’s useful life, and relevant metrics; also, scenario and sensitivity analyses
	13. Scenario Analysis (one per project)	PDF	N/A	Illustration of project cash flows, income statements, balance sheets, and key profitability metrics, IRR, and risk and debt service metrics under a plausible range of scenarios through the estimated useful life of the facility. Sensitivities should include upside and downside cases.
	14. CHIPS Incentives Request	Excel template or web form	N/A	Summary of requested dollar amounts for CHIPS Direct Funding and Loan and/or Loan Guarantees requested, including proposed terms



Section	Requested submission	Format	Max pages (Excluding supporting attachments)	Summary of Contents
	15. CHIPS Incentives Request Narrative	PDF	N/A	Justifications of size, appropriateness, and project IRR based on the CHIPS Incentives request
	16. CHIPS Loan or Loan Guarantee Request	PDF	N/A	Description of proposed terms for any Loans or Loan Guarantees requested and explanation of efforts to attract debt financing from other sources
Project Technical Feasibility	17. Technical Feasibility Narrative	PDF	20 per project	Description of organizational readiness, technology and manufacturing processes, and construction plan
	18. Environmental Questionnaire	PDF template	N/A	Submit a completed questionnaire available for download in the CHIPS application portal
Organization Information	19. Ownership, Legal Entity, and Organizational Structure	PDF	N/A	Detail of all parent companies, subsidiaries, affiliates, and other related entities, including any recent or upcoming organizational changes
	20. Managerial Capability	PDF	N/A	Approach to managerial oversight and governance of the project(s) from construction through the life of the facility. Include resumes of key management personnel and key personnel of contractors.
	21. Consortium Applicants	PDF (and web form, if available)	N/A	Key participants, roles, structure, and benefits of a consortium, if applicable
	22. Past Project History	PDF	N/A	Description of comparable facilities commissioned by the potential applicant or parent company in the last ten years
	23. Intellectual Property Security	PDF	N/A	Policies and procedures to combat cloning, counterfeiting, and relabeling of semiconductors, as applicable, as well as protecting semiconductor designs and other intellectual property associated with the manufacture of semiconductors
	24. Litigation and/or Conflicts	PDF	N/A	Disclosures of historical, current, or pending litigation for potential applicant, its corporate parent (if applicable), or any relevant party



Section	Requested submission	Format	Max pages (Excluding supporting attachments)	Summary of Contents
	25. Advisors and Key Partners	PDF (and web form, if available)	N/A	List of advisors who will represent the applicant before the Department in connection with its application and any partner named elsewhere in the application (e.g. contractor, investor in the project, workforce training partner, etc.)
Workforce Development Plan	26. Workforce Development Plan	PDF (and web form, if available)	30	Document expected workforce needs for each facility and a strategy to meet such needs. Also produce a workforce plan for the construction workforce. Identify overall financial resources that will be committed to these efforts.
Broader Impacts	27. Broader Impacts Narrative	PDF	30	Information related to broader impacts of project(s), including: <ul style="list-style-type: none"> • Commitments to future investment in the US semiconductor industry • Buyback commitment • Support for semiconductor research & development • Inclusive opportunities for businesses, • Commitment to climate & environmental responsibility • Community investments • Domestic content
Standard Forms	28, Upload forms provided	PDF templates	N/A	All applicants will be required to upload a minimum of two forms: SF-328 (Certificate Pertaining to Foreign Interests) and CD-511 (Certification Regarding Lobbying), and if applicable SF-LLL (Disclosure of Lobbying Activities)